

FIG. 1

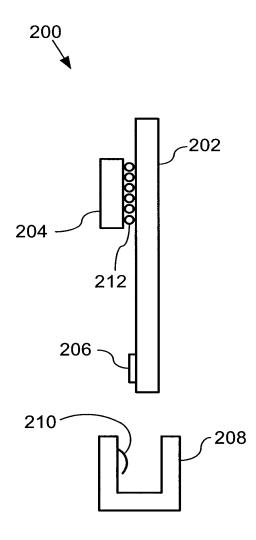


FIG. 2

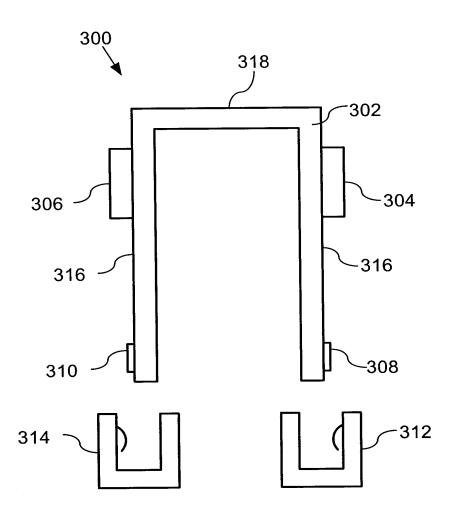


FIG. 3

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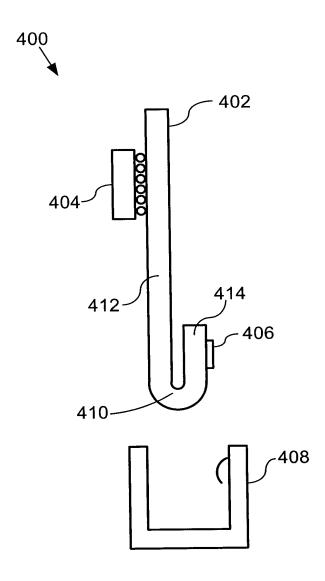


FIG. 4

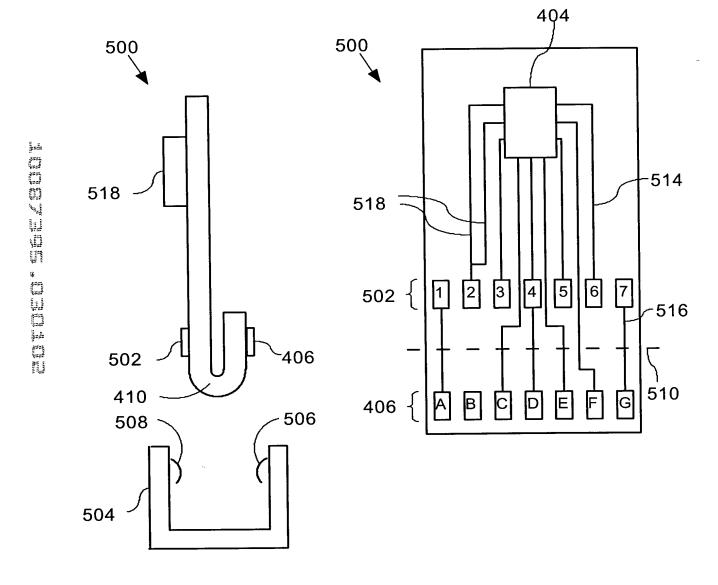


FIG. 5A

FIG. 5B

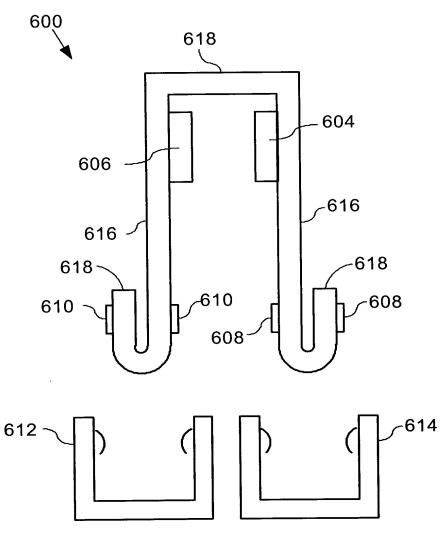


FIG. 6

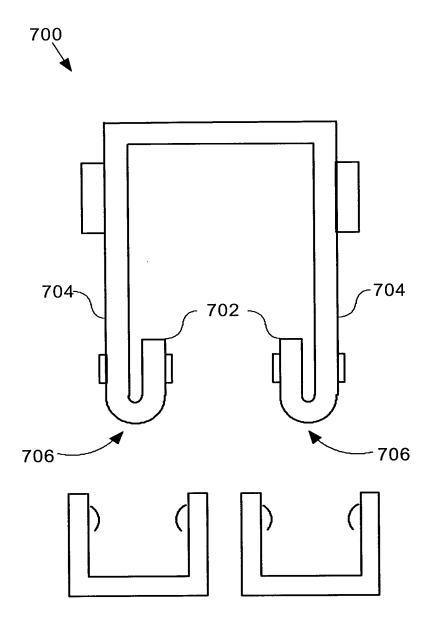


FIG. 7

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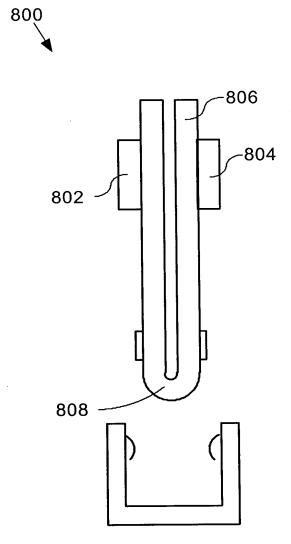


FIG. 8

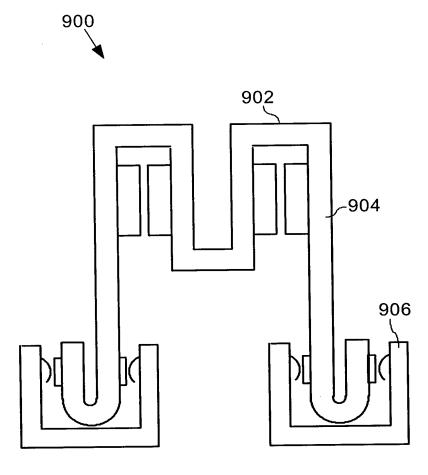


FIG. 9

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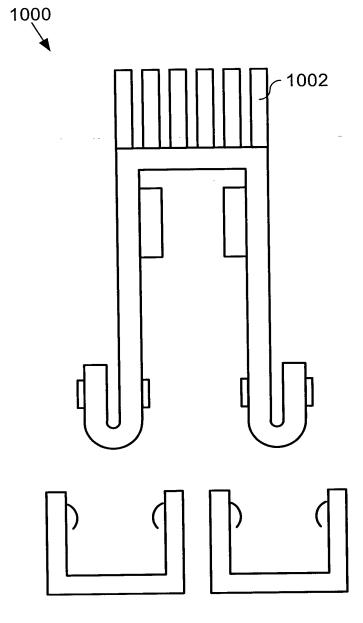


FIG. 10

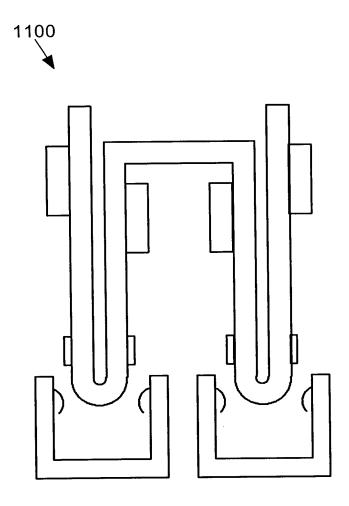


FIG. 11

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Providing a base layer 1204 Forming substrate 1202 Applying an insulating layer to first layer 1206 Coating insulating layer 1208 Etching traces onto the insulating layer 1210 Coupling a semiconductor to the insulating layer 1212 Bending substrate through 180 degrees 1214

FIG. 12